

DATICS-IMECS'09: Design, Analysis and Tools for Integrated Circuits and Systems

The *International Workshop DATICS-IMECS'09: Design, Analysis and Tools for Integrated Circuits and Systems* in the International MultiConference of Engineers and Computer Scientists 2009 (IMECS 2009) will take place in Hong Kong, 18-20 March, 2009.

The main target of the DATICS-IMECS'09 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all areas of design, analysis and tools for integrated circuits (e.g. digital, analog and mixed-signal circuits) and systems (e.g. real-time, hybrid and embedded systems). DATICS-IMECS'09 also focuses on the fields of formal methods, low power design methodologies for integrated circuits and wireless sensor networks (WSNs).

The *International Program Committee* (IPC) of DATICS-IMECS'09 consists of about 70 experts in the related fields of DATICS-IMECS'09 both from academia and industry. DATICS-IMECS'09 is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), International Software and Productivity Engineering Institute (USA), Intelligent Support Ltd., (United Kingdom), Miteos (Italy), M.O.S.T. (Italy), Electronic Center (Italy) and Legale Fiscale (Italy). DATICS-IMECS'09 is sponsored by LS Industrial Systems (South Korea) and Solari (Hong Kong).

DATICS-IMECS'09 received 24 full-paper submissions from 9 different countries around the world. These submissions were sent to the members of the IPC and additional reviewers for review. Every submission received at least two independent reviews. We would like to thank the IPC members and the reviewers for their hard work and dedication. The DATICS-IMECS'09 Technical Program includes 11 papers (acceptance rate of 45%) which are organised into lecture sessions.

On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-IMECS'09. We hope that you will enjoy the workshop and find the DATICS-IMECS'09 Technical Program exciting.

Ka Lok Man and Michele Mercaldi - DATICS-IMECS'09, IPC Chairs

DATICS-IMECS'09 International Program Committee and Technical Reviewers:

- Ka Lok Man, University College Cork, Ireland
- Michele Mercaldi, M.O.S.T., Italy
- Vladimir Hahanov, Kharkov National University of Radio Electronics, Ukraine
- Paolo Prinetto, Politecnico di Torino, Italy
- Massimo Poncino, Politecnico di Torino, Italy
- Alberto Macii, Politecnico di Torino, Italy
- Joongho Choi, University of Seoul, South Korea
- Wei Li, Fudan University, China
- Michel Schellekens, University College Cork, Ireland
- Emanuel Popovici, University College Cork, Ireland
- Jong-Kug Seon, System LSI Lab., LS Industrial Systems R&D Center, South Korea
- Umberto Rossi, STMicroelectronics, Italy
- Franco Fummi, University of Verona, Italy
- Graziano Pravadelli, University of Verona, Italy
- Yui Fai Lam, Hong Kong University of Science and Technology, Hong Kong
- Vladimir Pavlov, International Software and Productivity Engineering Institute, USA
- Ajay Patel, Intelligent Support Ltd, United Kingdom
- Jinfeng Huang, Philips & LiteOn Digital Solutions Netherlands, The Netherlands

- Thierry Vallee, Georgia Southern University, Statesboro, Georgia, USA
- Menouer Boubekour, University College Cork, Ireland
- Ana Sokolova, University of Salzburg, Austria
- Sergio Almerares, STMicroelectronics, Italy
- Monica Donno, Miteos, Italy
- Jun-Dong Cho, Sung Kyun Kwan University, South Korea
- AHM Zahirul Alam, International Islamic University Malaysia, Malaysia
- Gregory Provan, University College Cork, Ireland
- Miroslav N. Velez, Aries Design Automation, USA
- M. Nasir Uddin, Lakehead University, Canada
- Alexei Botchkarev, IEEE Canada Board of Directors
- Dragan Bosnacki, Eindhoven University of Technology, The Netherlands
- Dave Hickey, University College Cork, Ireland
- Maria O'Keeffe, University College Cork, Ireland
- Tomas Krilavičius, Vytautas Magnus University, Lithuania
- Milan Pastrnak, Siemens IT Solutions and Services, Slovakia
- John Herbert, University College Cork, Ireland
- Zhe-Ming Lu, Sun Yat-Sen University, China
- Jeng-Shyang Pan, National Kaohsiung University of Applied Sciences, Taiwan
- Chin-Chen Chang, Feng Chia University, Taiwan
- Mong-Fong Horng, Shu-Te University, Taiwan
- Liang Chen, University of Northern British Columbia, Canada
- Chee-Peng Lim, University of South Australia, Australia
- Ngo Quoc Tao, Vietnamese Academy of Science and Technology, Vietnam
- Suash Deb, C. V. Raman College of Engineering, India
- Salah Merniz, Mentouri University, Constantine, Algeria
- Oscar Valero, University of Balearic Islands, Spain
- Yang Yi, Sun Yat-Sen University, China
- Damien Woods, University of Seville, Spain
- Franck Veldrine, CEA, France
- Bruno Monsuez, ENSTA, France
- Kang Yen, Florida International University, USA
- Takenobu Matsuura, Tokai University, Japan
- R. Timothy Edwards, MultiGiG, Inc., USA
- Olga Tveretina, Karlsruhe University, Germany
- Maria Helena Fino, Universidade Nova De Lisboa, Portugal
- Adrian Patrick O'Riordan, University College Cork, Ireland
- Grzegorz Labiak, University of Zielona Gora, Poland
- M.S. Gaur, Malaviya National Institute of Technology, Jaipur, India
- Jian Chang, Texas Instruments, Inc, USA
- Yeh-Ching Chung, National Tsing-Hua University, Taiwan
- Anna Derezińska, Warsaw University of Technology, Poland
- Kyoung-Rok Cho, Chungbuk National University, South Korea
- Yong Zhang, Shenzhen University, China
- R. Liutkevičius, Vytautas Magnus University, Kaunas, Lithuania
- Yuanyuan Zeng, University College Cork, Ireland
- Arkadiusz Bukowiec, University of Zielona Gora, Poland
- Paris Kitsos, Hellenic Open University, Patras, Greece
- Peter Westermann, Technical University of Dortmund, Germany
- Tom English, University College Cork, Ireland
- Miquel Moreto Planas, Technical University of Catalonia, Spain
- Chelho Chung, System Semiconductor/Central R&D Center, LS Industrial Systems, South Korea
- Amlan Chakrabarti, University of Calcutta, India
- Chi-Un Lei, University of Hong Kong, Hong Kong
- Mohamed Bamakhrama, ST-NXP Wireless, The Netherlands
- B. Rajendra Naik, Osmania University, India
- Felipe Klein, State University of Campinas (UNICAMP), Brazil
- Sean Harte, Tyndall, University College Cork, Ireland
- Jun Wang, University College Cork, Ireland